

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5021586	(bond bonding terminal electrode pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 21:32
L2	773465	(substrate carrier board ((printed circuit circuitry wiring) adj4 board)) with 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 21:36
L3	33034	2 with (package microelectronic packaging packged)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 21:39
L4	9384	(bottom top first second under upper) with 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 21:40
L5	236	(available unused unusing open free unoccupied unoccupy unoccuping) with 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 22:28
L6	6791	(assembly structure) and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 22:28
L7	433558	(available unused unusing open free unoccupied unoccupy unoccuping) with 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 22:28
L8	1702	4 and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 22:29